

10052143
01/17/02

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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10052143	FILING DATE 01/17/2002	CLASS 257	SUBCLASS 777	GAU 2827	EXAMINER ZARNEKE
**APPLICANTS: Honda Hirokazu;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/712,105 11/14/2000					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 325770/1999 11/16/1999					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials		NEC 00USFP553 DIV			
TITLE : Semiconductor device and manufacturing method the same					
U.S. DEPT. OF COMM /PAT. & TM-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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